

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	((("6180696") or ("6190940")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/06 16:08
S2	8	((("5864178") or ("6410415")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/06 16:14
S3	2	("20020060368").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/07 20:23
S4	4606354	@ad>"20000405" @rlad>"20000405" @pt1d>"20000405"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:38
S5	1054241	chip die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:38
S7	568576	wet wett\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:40
S8	155530	\$10silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:41
S9	142747	silan\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:41
S10	175971	S8 S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:41

S11	6169	S5 with S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:42
S12	10	S11 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:42
S13	1	S12 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:42
S14	5819	underfil\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:48
S15	8	S14 with S5 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:43
S16	2	S15 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:43
S17	20	("4999699" "5121190" "5128746" "5194930" "5376403" "5644003").PN. OR ("6180696").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/06 16:45
S18	7	S17 not S4	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/06 16:47
S21	23	S14 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:49
S22	3	S21 not (S16 S18 S4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:54

S23	32767	coupling with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:54
S24	11	S14 with S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:55
S25	4	S24 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:55
S26	213	S5 with S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 16:55
S27	125	S26 not (S16 S18 S22 S25 S4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:16
S28	75949	surface! adj tension	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:16
S29	188	S28 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:17
S30	30	S29 with (S5 S7 S14)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:17
S31	16	S30 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:17
S32	36	("2893896" "2976185" "3036930" "3134684" "3250642" "3297462" "3343976" "3361587" "3364056" "3451838" "3453248" "3457323").PN. OR ("3619246").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/06 17:28

S33	36	S32 not S4	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/06 17:35
S34	3	("3619246").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/06 17:37
S35	158	S29 not S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:38
S36	110	S35 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:42
S37	57	S28 with S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:42
S38	5	S37 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:42
S39	0	S38 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:42
S40	22	S37 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:50
S41	39226	monolayer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:50
S42	0	S41 with S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/06 17:50

S43	155530	\$10silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:24
S44	142747	silan\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:24
S45	175971	S43 S44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:24
S46	9520	liquid with S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:24
S47	1896789	semiconductor integrated adj circuit ic "438"/\$.ccls. "257"/\$.ccls 228/180.22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:25
S48	1826	S46 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:25
S50	75949	surface! adj tension	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:26
S51	162	S48 and S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:26
S52	4606354	@ad>"20000405" @rlad>"20000405" @pt1d>"20000405"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:26
S53	57	S51 not S52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/07 20:45

S54	3	("3619246").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/07 20:45
S55	36	("2893896" "2976185" "3036930" "3134684" "3250642" "3297462" "3343976" "3361587" "3364056" "3451838" "3453248" "3457323").PN. OR ("3619246").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/07 20:47
S56	36	S55 not S52	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/07 20:48
S57	8	S56 and S45	US-PGPUB; USPAT; USOCR	OR	ON	2004/08/07 21:27
S58	2	("6074895").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/07 22:44